

**PRODUCT
DATASHEET**

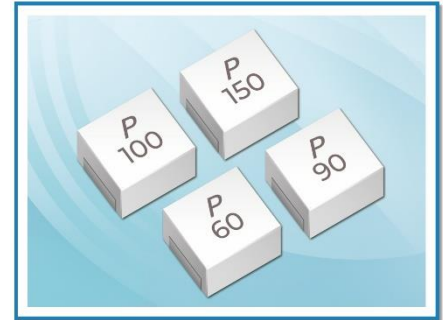


SMFF5040 Series Surface Mount Fuses Devices

SMFF5040 Series Surface Mount Fuses Devices

Description

Polytronics SMFF5040 series surface mount fuse is in a compact miniature rectangular shape, offering up to 150A/125V rating with high interrupt of 1000A to meet various applications. The fusing element and the terminals are integrally stamped and formed for utmost reliability. Thermosetting adhesive filling design ensures that the product is completely lead-free to meets RoHS and REACH requirements.







Features

- Fast Acting
- Compact rectangular size
- Enhanced thermal cycling endurance
- Ceramic body design
- Excellent environmental integrity
- MSL 1



Application

- AI, blade, and edge servers
- High-end power supplies
- Power Distribution Units
- Industrial power tools
- Battery Management System
- Energy Storage System
- Cooling fan system
- Voltage regulator module

Agency Approval and Environmental Compliance

Agency	File Number	Regulation	Standard
	UL/CSA: Pending		2011/65/EU
	TÜV: Pending		IEC 61249-2-21:2003

Electrical Characteristics

Part Number	Marking	Current Rating (A)	Voltage Rating	Interrupting Rating	Typical Cold DCR† (mΩ)	Typical I ² T‡ (A ² S)	Agency Approval	
								
SMFF5040P060	60	60	125V	1000A 125V DC	0.98	2100	Pending	Pending
SMFF5040P070	70	70			0.75	2800	Pending	Pending
SMFF5040P080	80	80			0.57	3400	Pending	Pending
SMFF5040P090	90	90			0.52	4000	Pending	Pending
SMFF5040P100	100	100		5000A 100VDC	0.46	4300	Pending	Pending
SMFF5040P125	125	125			0.33	6250	Pending	Pending
SMFF5040P150	150	150			0.23	9000	Pending	Pending

† Measured at ≤ 10% rated current and 25°C

‡ Melting I²T at 10 times of rated current

SMFF5040 Series Surface Mount Fuses Devices

Electrical Specification

Ampere Rating	% of Current Rating	Opening Time
60A~150A	100%	4 Hours Min.
	200%	60 Seconds Max.
	1000%	10 mSec. Min.

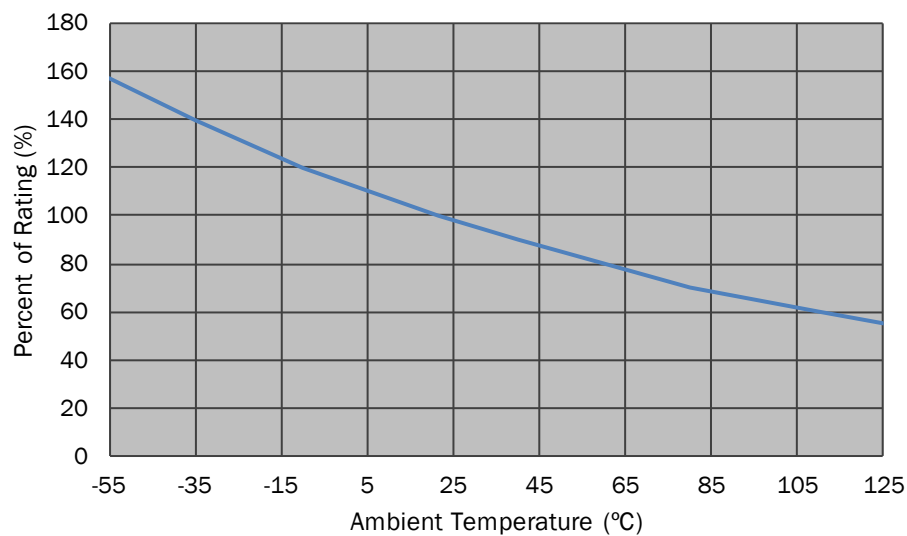
Physical Specifications

Materials	Body: Ceramic Element: Copper over-plated with 100% tin
Solderability	MIL-STD-202
Soldering Parameters	Wave Solder: 260°C, 10 seconds max. Reflow Solder: 260°C, 20 seconds max. Hand Solder: 350°C, 5 seconds max.

Environmental Specifications

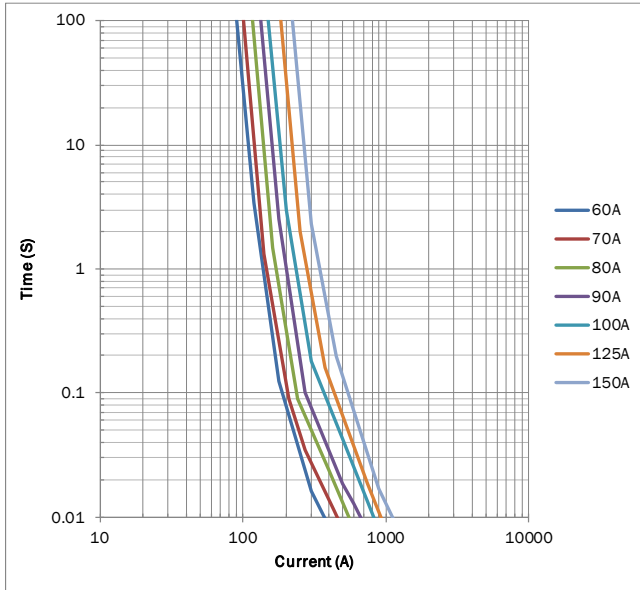
Operating Temperature	-55°C to 125°C
------------------------------	----------------

Thermal Derating Curve

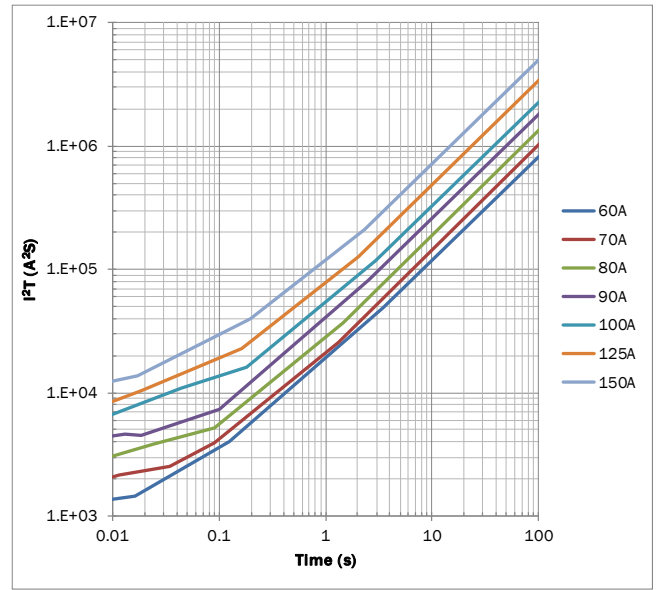


SMFF5040 Series Surface Mount Fuses Devices

Time-Current Curve



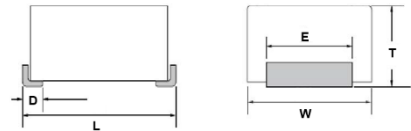
I²T vs Time Curve



Physical Dimensions (mm.)

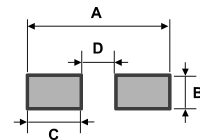
Dimensions (mm)

L	W	T	D	E
12.10±0.50	10.00±0.30	6.80±0.30	1.80±0.30	8.00±0.30



Recommended Solder Pad Dimension (mm)

A	B	C	D
14.00±0.30	10.00±0.30	3.00±0.30	8.00±0.30



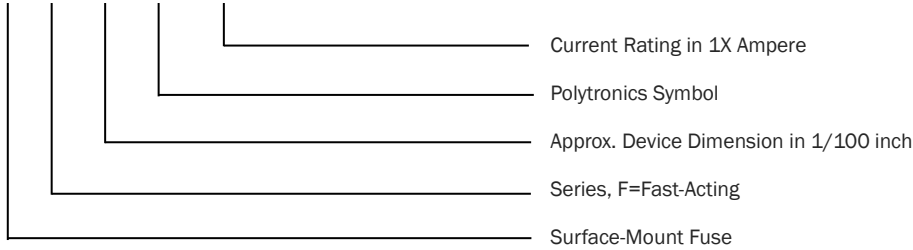
Dimensions of Standard Test Board (mm)

Ampere Rating	Board Thickness	Copper Layer Thickness	Copper Trace Width
60A~150A	1.6	0.210	33

SMFF5040 Series Surface Mount Fuses Devices

Part Number System

SMF F 5040 P □□□

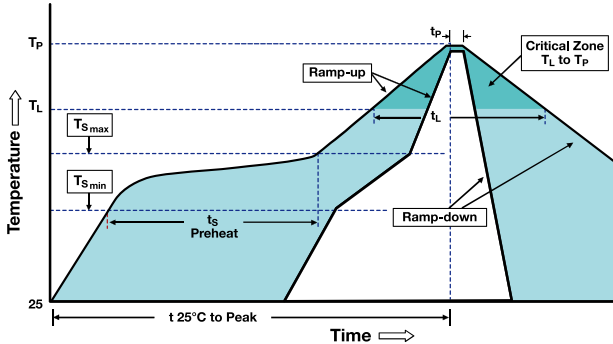


Reliability Test

Characteristics	Test condition / Methods	Requirement	Test Reference
Time/Current	100% In	No Fusing; 4 hours min.	UL248-14
	200% In	≤ 60 sec	Refer to Spec
	1000% In	≥ 10 msec	IEC60127-4
Insulation Resistance	Test Condition A, 0.01MΩ Min.	0.01MΩ Min.	MIL-STD-202 Method 302
Interrupting Ability	3000A/125V DC 5000A/100V DC	Without permanent arcing, ignition and bursting of fuse link	UL 248-14 IEC60127-4
Solderability	240°C ± 5°C, 3 sec ± 0.5sec	95% coverage min	IEC 60127-4 IEC 60068-2-20 MIL-STD-202
Resistance to Soldering	260°C ± 5°C, 10 sec ± 0.5sec	ΔR : <10%	MIL-STD-202 Method 210
Moisture Resistance	85°C ± 3°C, 85% ± 5% RH, 1000 hours	ΔR : <10%	MIL-STD-202 Method 106
Low Temperature Storage	55°C ± 3°C, 1000 hours	ΔR : <10%	IEC60068-2-1
High temperature Storage	125°C ± 2°C, 1000 hours	ΔR : <10%	IEC60068-2-2
Salt Spray	5% salt solution, 72 hours	ΔR : <10%	MIL-STD-202 Method 101
Thermal Shock	100 cycles, 65°C / +125°C 30 min. at each temperature zone	ΔR : <10%	MIL-STD-202 Method 107
Vibration	Amplitude 10Hz ~ 55Hz in 1 min. 2 hours each XYZ, total 6 hours.	ΔR : <10%	MIL-STD-202 Method 201
Mechanical shock	100G's peak amplitude, saw tooth wave 6ms duration, 3 cycles XYZ+xyz = 18	ΔR : <10%	MIL-STD-202 Method 213

SMFF5040 Series Surface Mount Fuses Devices

Soldering Parameters

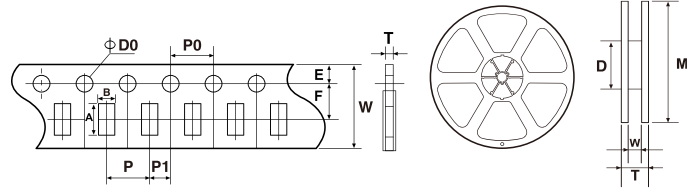


Average Ramp-Up Rate (TS _{max} to TP)	3°C/second max.
Preheat	
-Temperature Min (TS _{min})	150°C
-Temperature Max (TS _{max})	200°C
-Time (TS _{min} to TS _{max})	60-120 seconds
Time maintained above:	
-Temperature (TL)	217°C
-Time (tL)	60-150 seconds
Peak Temperature (TP)	260°C
Time within 5°C of actual Peak Temperature (tp)	20 seconds max.
Ramp-Down Rate	6°C /second max.
Time 25°C to Peak Temperature	8 minutes max.

Note 1: All temperature refer to top side of the package, measured on the package body surface.

Note 2: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Tape & Reel Specification (mm.)



A		M	∅ 330.0 ± 2.0
B		W	
W	24.00 ± 0.30	T	
F		A	
E		B	
P		C	
P0		D	
P1			
D0			
T			

Packaging Quantity

Part Number	Tape & Reel Quantity
SMFF5040PXXX	500

Storage

- The ambient temperature recommended for storage shall be between 5°C ~30°C.
- The relative humidity recommended for storage shall be between 25%RH~60%RH.
- Sealed plastic bags with desiccant shall be used to reduce the oxidation of the termination and shall only be opened prior to use.
- The products shall not be stored in areas where harmful gases containing sulfur or chlorine are present.

Warning

- Fuse product is not recommended for any type of coating. Polytronics is not responsible for any damage directly or indirectly related to the coating.
- For copper layer thickness or copper trace width different from the standard test board, fusing characteristics needs to be verified to ensure product performance meet user requirement.